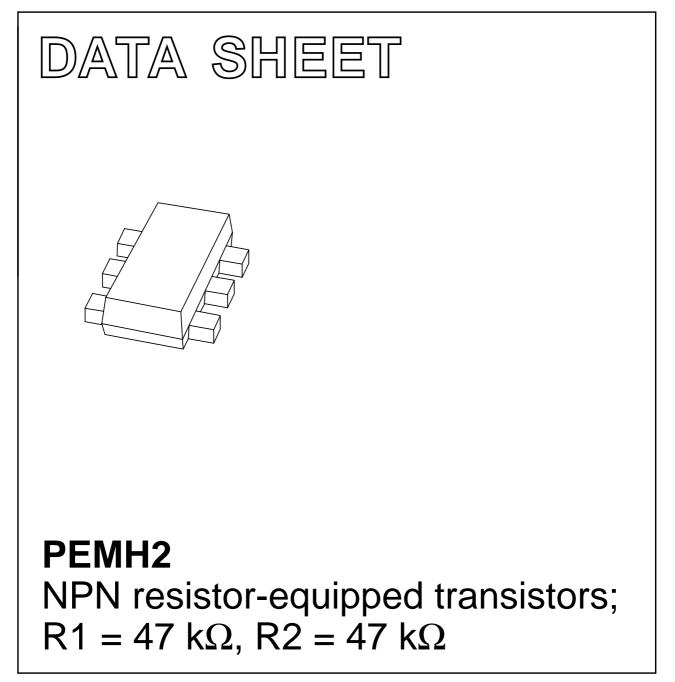
DISCRETE SEMICONDUCTORS



Preliminary specification

2001 Oct 22



FEATURES

- 300 mW total power dissipation
- Very small 1.6×1.2 mm ultra thin package
- Self alignment during soldering due to straight leadsReplaces two SC-75/SC-89 packaged transistors on
- Reduces required PCB area
- Reduced pick and place costs.

APPLICATIONS

same PCB area

- · General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

DESCRIPTION

NPN resistor-equipped transistors in a SOT666 plastic package.

MARKING

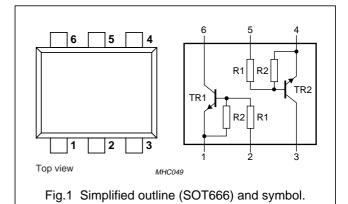
TYPE NUMBER	MARKING CODE		
PEMH2	Z2		

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT	
V _{CEO}	collector-emitter voltage	50	V	
I _{CM}	peak collector current	100	mA	
TR1	NPN	_	-	
TR2	NPN	_	_	
R1	bias resistor	47	kΩ	
R2	bias resistor	47	kΩ	

PINNING

PIN	DESCRIPTION	
1, 4	emitter	TR1; TR2
2, 5	base	TR1; TR2
6, 3	collector	TR1; TR2



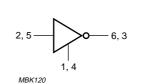


Fig.2 Equivalent inverter symbol.

PEMH2

PEMH2

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transi	stor	·		1	
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	_	50	V
V _{EBO}	emitter-base voltage	open collector	_	10	V
Vi	input voltage				
	positive		_	+40	V
	negative		_	-10	V
lo	output current (DC)		_	100	mA
I _{CM}	peak collector current		_	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	200	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C
Per device	9	·	·		
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	300	mW

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER CONDITIONS		VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	notes 1 and 2	416	K/W	

Notes

1. Transistor mounted on an FR4 printed-circuit board.

2. The only recommended soldering method is reflow soldering.

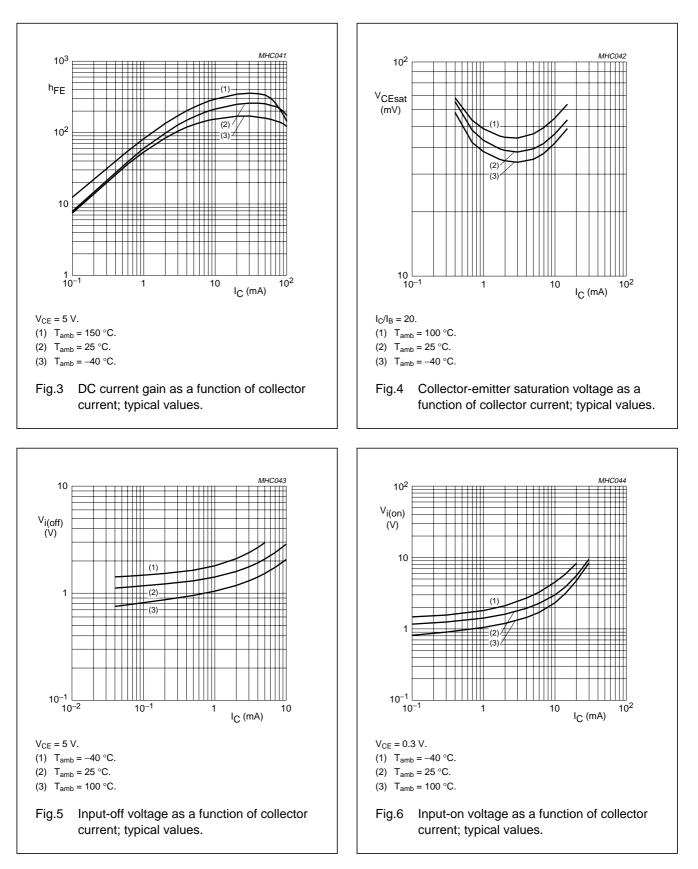
PEMH2

CHARACTERISTICS

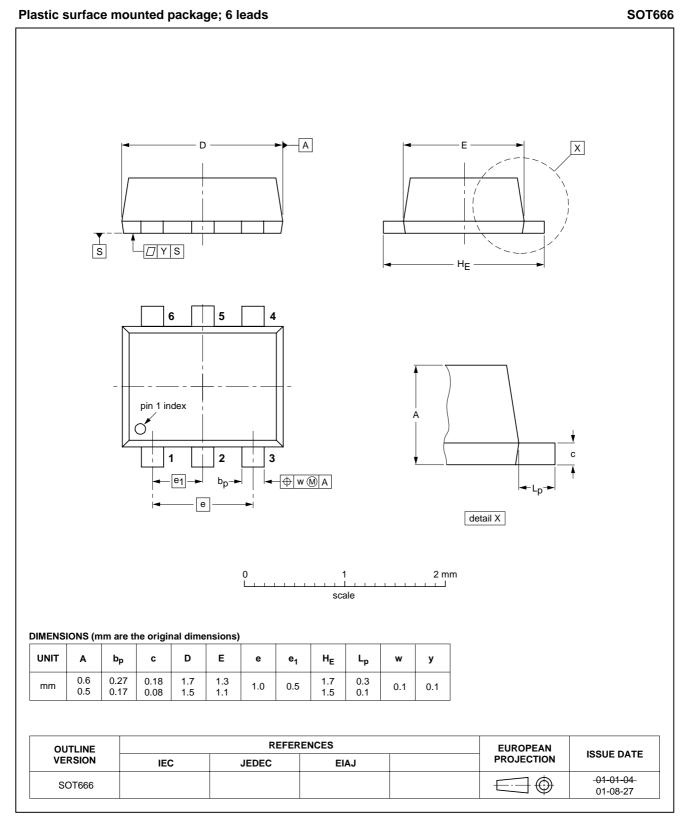
 T_{amb} = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transis	Per transistor					
I _{CBO}	collector-base cut-off current	$V_{CB} = 50 \text{ V}; \text{ I}_{E} = 0$	-	-	100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = 50 \text{ V}; \text{ I}_{B} = 0$	-	_	1	μA
		$V_{CE} = 30 \text{ V}; \text{ I}_{B} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$	-	-	50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 V; I_{C} = 0$	-	-	90	μA
h _{FE}	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 5 \text{ mA}$	80	-	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	-	-	150	mV
V _{i(off)}	input off voltage	$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 100 \mu\text{A}$	-	1.2	0.8	V
V _{i(on)}	input on voltage	$V_{CE} = 0.3 \text{ V}; I_{C} = 2 \text{ mA}$	3	1.6	-	V
R1	input resistor		33	47	61	kΩ
R2 R1	resistor ratio		0.8	1	1.2	
C _c	collector capacitance	I _E = i _e = 0; V _{CB} = 10 V; f = 1 MHz	-	-	2.5	pF

PEMH2



PACKAGE OUTLINE



PEMH2

PEMH2

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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